L Number	Hits	Search Text	DB	Time stamp
34	5	("5189812" "5325604" "5458687" "5609720"	USPAT	2003/07/29 10:50
•		"5791895").PN.		
64	15	("4469529" "5108792" "5345534" "5551985" "5595606"	USPAT	2003/07/29 12:04
		"5624499" "5650082" "5683518" "5708755" "5711815"		
		"5846476" "5889258" "5900177" "5937142"		
		"5970214").PN.		
65	106249	(adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3	USPAT;	2003/07/29 12:09
	, , , , , , , , , , , , , , , , , , , ,	rais\$3) near5 temperature near12 (antifreeze anti-freeze	US-PGPUB;	
		glycol ethyleneglycol water refrigerant ((((heat near2	EPO; JPO;	
		transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2	DERWENT	
		exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant	IBM_TDB	
		or (cooling near2 (fluid medium liquid gas vapor)))) (thermal	-	
		near2 transfer\$4 near2 (fluid medium liquid gas vapor))		
		(thermal near2 exchang\$3 near2 (fluid medium liquid gas		
		(vapor))))		
66	26170	(adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3	USPAT;	2003/07/29 12:10
		rais\$3) near12 (((flow\$3 circulat\$3 suppl\$4) near3 (rate	US-PGPUB;	
		speed)) near8 (antifreeze anti-freeze glycol ethyleneglycol	EPO; JPO;	
		water refrigerant ((((heat near2 transfer\$4 near2 (fluid	DERWENT;	
		medium liquid gas vapor)) (heat near2 exchang\$3 near2	IBM_TDB	
		(fluid medium liquid gas vapor))) (coolant or (cooling near2	_	
		(fluid medium liquid gas vapor)))) (thermal near2 transfer\$4		
		near2 (fluid medium liquid gas vapor)) (thermal near2		
		exchang\$3 near2 (fluid medium liquid gas vapor)))))		
67	611	(adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3	USPAT;	2003/07/29 17:00
•	• • • • • • • • • • • • • • • • • • • •	rais\$3) near5 (power energy) near10 (process lamp ion	US-PGPUB;	
		electron) near10 (temperature near3 (wafer substrate	EPO; JPO;	
		workpiece plate susceptor pedestal support table chuck	DERWENT:	
		holder))	IBM_TDB	
69	18	((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3	USPAT;	2003/07/29 12:14
		rais\$3) near12 (((flow\$3 circulat\$3 suppl\$4) near3 (rate	US-PGPUB;	
		speed)) near8 (antifreeze anti-freeze glycol ethyleneglycol	EPO; JPO;	
		water refrigerant ((((heat near2 transfer\$4 near2 (fluid	DERWENT;	
		medium liquid gas vapor)) (heat near2 exchang\$3 near2	IBM_TDB	
		(fluid medium liquid gas vapor))) (coolant or (cooling near2	_	
		(fluid medium liquid gas vapor)))) (thermal near2 transfer\$4		
		near2 (fluid medium liquid gas vapor)) (thermal near2		
		exchang\$3 near2 (fluid medium liquid gas vapor)))))) and		
		((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3		
		rais\$3) near5 (power energy) near10 (process lamp ion		
		electron) near10 (temperature near3 (wafer substrate		
		workpiece plate susceptor pedestal support table chuck		
		holder)))		
70	41	5200023.URPN.	USPAT	2003/07/29 12:16
71	9	("3664942" "3718757" "4396478" "4675072" "4883560"	USPAT	2003/07/29 12:46
		"4913790" "4919542" "4936967" "4971653").PN.		
72	11	4396478.URPN.	USPAT	2003/07/29 12:55
73	18	("4184480" "4409511" "4427378" "4680447" "4920918"	USPAT	2003/07/29 13:15
		"4945251" "5145716" "5152060" "5743643" "5762713"		
	•	"5781693" "5790751" "5863334" "5960158" "6143079"		
		"6148761" "6284051" "6435869").PN.		
68	68	((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3	USPAT;	2003/07/29 14:42
		rais\$3) near5 temperature near12 (antifreeze anti-freeze	US-PGPUB;	
		glycol ethyleneglycol water refrigerant ((((heat near2	EPO; JPO;	
		transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2	DERWENT;	
		exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant	IBM_TDB	
		or (cooling near2 (fluid medium liquid gas vapor)))) (thermal		
ļ	*	near2 transfer\$4 near2 (fluid medium liquid gas vapor))		
		(thermal near2 exchang\$3 near2 (fluid medium liquid gas		
		vapor)))))) and ((adjust\$4 control\$4 var\$4 increas\$3		
ļ		decreas\$3 lower\$3 rais\$3) near5 (power energy) near10		
j		(process lamp ion electron) near10 (temperature near3		
İ		(wafer substrate workpiece plate susceptor pedestal support		
Į		table chuck holder)))		
		5:40:10 DM Page 1	<u> </u>	L

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74	55	(((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3	USPAT;	2003/07/29 16:58
		rais\$3) near5 temperature near12 (antifreeze anti-freeze	US-PGPUB;	
		glycol ethyleneglycol water refrigerant ((((heat near2	EPO; JPO;	
		transfer\$4 near2 (fluid medium liquid gas vapor)) (heat near2	DERWENT;	
		exchang\$3 near2 (fluid medium liquid gas vapor))) (coolant	IBM_TDB	
		or (cooling near2 (fluid medium liquid gas vapor)))) (thermal	·=··· <u>=</u> ·-=	
		near2 transfer\$4 near2 (fluid medium liquid gas vapor))		
		(thermal near2 exchang\$3 near2 (fluid medium liquid gas		
		vapor))))) and ((adjust\$4 control\$4 var\$4 increas\$3	-	
		decreas\$3 lower\$3 rais\$3) near5 (power energy) near10		
		(process lamp ion electron) near10 (temperature near3		
		(wafer substrate workpiece plate susceptor pedestal support		
		table chuck holder)))) not (((adjust\$4 control\$4 var\$4		
		increas\$3 decreas\$3 lower\$3 rais\$3) near12 (((flow\$3		
		circulat\$3 suppl\$4) near3 (rate speed)) near8 (antifreeze		
		anti-freeze glycol ethyleneglycol water refrigerant ((((heat		
		near2 transfer\$4 near2 (fluid medium liquid gas vapor)) (heat		
		near2 exchang\$3 near2 (fluid medium liquid gas vapor)))		
		(coolant or (cooling near2 (fluid medium liquid gas vapor))))		
		(thermal near2 transfer\$4 near2 (fluid medium liquid gas		
		vapor)) (thermal near2 exchang\$3 near2 (fluid medium liquid		
		gas vapor)))))) and ((adjust\$4 control\$4 var\$4 increas\$3		
		decreas\$3 lower\$3 rais\$3) near5 (power energy) near10		
		(process lamp ion electron) near10 (temperature near3		
		(wafer substrate workpiece plate susceptor pedestal support		
		table chuck holder))))		
75	13	5605600.URPN.	USPAT	2003/07/29 16:27
76	13	5605600.URPN.	USPAT	2003/07/29 16:27
77	19	("4261762" "4457359" "4508161" "4533430" "4855017"	USPAT	2003/07/29 16:27
		"4903754" "4949783" "4963713" "5001423" "5093579"		
		"5155331" "5191218" "5203958" "5267607" "5270266"		
		"5290381" "5320982" "5366002" "5458734").PN.		
78	1582	((control\$4 adjust\$4) near3 temperature near10 (wafer	USPAT;	2003/07/29 17:00
		substrate workpiece plate susceptor pedestal support table	US-PGPUB;	
		chuck holder)).ti.	EPO; JPO;	
		<i>"</i>	DERWENT;	
			IBM TDB	
79	1017	(((control\$4 adjust\$4) near3 temperature near10 (wafer	USPAT;	2003/07/29 17:21
. •		substrate workpiece plate susceptor pedestal support table	US-PGPUB;	
		chuck holder)).ti.) and (VLSI ULSI semiconductor wafer	EPO; JPO;	
		substrate (integrated adj circuit))	DERWENT;	
		Substitute (integrated day on early)	IBM TDB	
80	18	((adjust\$4 control\$4 var\$4 increas\$3 decreas\$3 lower\$3	USPAT;	2003/07/29 17:21
	10	rais\$3) near5 (power energy) near10 (process lamp ion	US-PGPUB;	
		electron) near10 (temperature near3 (wafer substrate	EPO; JPO;	
		workpiece plate susceptor pedestal support table chuck	DERWENT;	
		holder))) and ((((control\$4 adjust\$4) near3 temperature	IBM TDB	
		near10 (wafer substrate workpiece plate susceptor pedestal	.5 55	
		support table chuck holder)).ti.) and (VLSI ULSI		
		semiconductor wafer substrate (integrated adj circuit)))		
	ı	Settinooniquotot Water Substrate (Integrated adj Circuit)))	1	I